

Development of a MEMS

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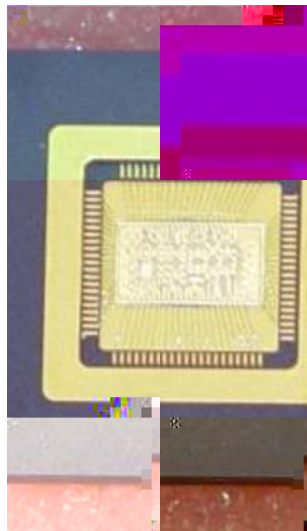
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Many MEMS work in a ceramic package, with a cavity under vacuum. A solder ring under v

vacuum. The approach we take through MEMS device inside it, put a lead cap (to the right). The sealing process



This project aims to study the sealing process. Once the system is sealed, the team needs to study potential leakage

vacuum system that includes manipulating the device. The challenges include thermal expansion / contraction and applying a desired level of force onto the device. To achieve this, the team needs to test package

The team will be provided with the necessary hardware. Further information can be obtained from Dr Bahreyni by November 20, 2013.

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A vacuum packaging system with control over: